# Technical Program Committee 2017

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Jam-Wem Lee, *TSMC*
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Teruo Suzuki, *SocioNext*
Benjamin Van Camp, *Sofics*
Yuan Wang, *Peking University*
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## ESD Protection in Bipolar, RF, High Voltage, and BCD Technologies
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Carol Rouying Zhan, *NXP Semiconductors*

## Numerical Modeling and Simulation for On-Chip ESD Protection
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Dionyz Pogany, *Vienna Technical University*
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## EOS/ESD Failure Analysis, Troubleshooting, and Case Studies
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Mariano Dissegna, *Texas Instruments, Inc.*
Tim Iben, *IBM*
Bart Keppens, *Sofics*
Manjunatha Prabhu, *GLOBALFOUNDRIES*
Sandeep Sangameswaran, *Philips Semiconductors*
Yu-Ti Su, *TSMC*

## Device Testing: Testers, Methods, and Correlation Issues
**Sub-Committee Chair:** David Eppes, *AMD*
Michael Chaine, *Micron Technology*
Thomas Chang, *GLOBALFOUNDRIES*
Tim Maloney, *Center for Analytic Insight*
Tom Meuse, *Thermo Fisher Scientific*
Josh Morris, *Intel*
Paul Phillips, *Phasix ESD*
Masanori Sawada. *HANWA Electronics*
Scott Ward, *Texas Instruments, Inc.*

## System Level EOS/ESD/EMC/HMM
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Jeffrey Dunnihoo, *Pragma Design*
Fabrice Caignet, *LAAS/CNRS*
Charvaka Duvvury, *ESD Consulting LLC*
Harald Gossner, *Intel Deutschland GmbH*
David Johnsson, *HPPI*
Nathaniel Peachey, *Qorvo*

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Efraim Aharoni, *Tower Semiconductor*
Jonathan Brodsky, *Texas Instruments, Inc.*
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Eleonora Gevinti, *STMicroelectronics*
Matthew Hogan, *Mentor – A Siemens Business*
Souvick Mitra, *GLOBALFOUNDRIES*
Nitesh Trivedi, *Intel Corporation*

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**Sub-Committee Co-Chair:** Michelle Lam, *IBM*
Cheryl Checketts, *ESTATEC*
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Chuck McClain, *Micron Technology*
Dale Parkin, *Seagate Technology*
Jeff Salisbury, *Finisar*
Jay Skolnik, *Skolnik Technical*
Matt Strickland, *L3 Technologies, Inc.*
Scott Ward, *Texas Instruments, Inc.*
Joshua Yoo, *Core Insight, Inc.*